Siksha 'O' Anusandhan
(Deemed to be University)

CII
Center for Inovation and Incubation

NOTICE INVITING TENDER (NIT)

ADVERTISED TENDER ENQUIRY (ATE)

SUPPLY, INSTALLATION, TESTING, COMMISSIONING AND TRAINING OF SMT ASSEMBLY, PRODUCTION SUPPORT, PCB FABRICATION, PROTOTYPING AND INSPECTION EQUIPMENT

SOA-CII (SOA Centre for Innovation & Incubation)

Siksha 'O' Anusandhan (Deemed to be University), Bhubaneswar, Odisha

Tender Particulars	Details
Tender Reference No.	SOA-CII/2026/PROC/001
Date of Issue / Publication	11.11.2026
Bid validity	90 days from the last date prescribed for receipt of bids
Last date and time for receipt of bids	
Date and time of opening of Financial Bids	To be notified to technically qualified bidders
Bid submission method	Physical submission in sealed two-bid envelopes
Contact Person	Prof. Renu Sharma
Contact Email	renusharma@soa.ac.in
Contact Phone	7377068897
Issued by	SOA-CII (SOA Centre for Innovation & Incubation)

IMPORTANT: Bidders shall read the complete tender document and submit both bids in the manner prescribed herein.

1. INTRODUCTION

SOA-CII (SOA Centre for Innovation & Incubation) has been incorporated under Section 8 of the Companies Act, 2013 to provide a dedicated platform for innovation, incubation, technology-based entrepreneurship and the development of start-up ventures for the University and the region. SOA-CII aims to build a strong Health Tech and MedTech innovation ecosystem by supporting the development, validation, incubation and commercialisation of technology-driven solutions in healthcare and medical technology. The Centre promotes collaboration among academia, clinicians, researchers, innovators, industry, investors and start-ups.

2. INVITATION AND SCOPE OF PROCUREMENT

SOA-CII invites sealed bids from eligible manufacturers, authorised dealers, distributors or system integrators for the supply, installation, testing, commissioning and training of the equipment described in the Schedule of Requirements.

The procurement process shall be governed by the applicable procurement rules, guidelines and instructions of the Government of Odisha, including the Odisha General Financial Rules (OGFR), 2023, as amended from time to time, wherever applicable, and the relevant terms and conditions of the funding agency and the Host Institution.

2.1 Schedule of Requirements

Item No.	Specifications	Qty.
1	**PCB Automated Component Assembly setup**	
A.	**Advance High-Speed Pick & Place Machine** • Placement Head Gantry: 6 Nozzles Head • Vision Alignment: Flying Vision • Maximum Placement Rate: 14000CPH • Maximum Placement Rate: 9000CPH • Feeder Capacity: 53x Tape / Reel (8mm) • Minimum Component Size: 0201 • Maximum Component Size: 1.57" (40mm) Square Body • Max. Component Height: (Nozzle Z-Axis Max Travel) 0.629" (16mm) • Placement Accuracy: ±10um • Motion Feedback Control: (Right-Left) / (Left-Right) SPM/IBG • Compressed Air: >0.6MPa, max-flow-rate 37L/min | Oil Free • Supported Reel Size: Tape/Reel (Electric/Pneumatic), Vibration Tube, Waffle Tray • Cut Reel Feeder: Stack 8mm to 44mm size • Max. Board Dimension: 17.1" x 11.8" (460mm x 300mm) | Possible lengths up to 800mm • X axis Drive Type: WON Linear Guide / TBI Grinding screw C5 - 1632 • Y axis Drive Type: WON Linear Guide / TBI Grinding screw C5 - 1632 • Control System: Closed Loop Servo • Electricity Supply: 220VAC, 500W • Type of Feeders: Pneumatic + Electrical • Vibrating Feeder: Selectable • Decibel Rating: 55-60 dB (µV/m) at 10m	1
B.	**SMT Feeders** • Pneumtic Reel Feeder - 8mm • Pneumtic Reel Feeder - 12mm	1

	• Pneumtic Reel Feeder - 16mm • Pneumtic Reel Feeder- 24mm	
C.	**Automatic Solder Paste Printer** • **Frame Size:** 400 * 300 mm - 650 * 550 mm • **PCB Size:** 50 * 50 mm - 450 * 350 mm • **PCB Thickness:** 0.4 - 4 mm • **PCB Warpage:** < 1% • **Tansfer height:** 885 - 920 mm • **Demoulding speed:** 0.1 - 30 mm/s • **Demoulding length:** 0 - 10 mm • **Power supply:** 220 V / 110 V • **Maximum board weight:** 4 kg • **Maximum bottom gap:** 25 mm • **Printing pressure:** 0.5 - 10 Kg • **Platform adjustment range:** X:±5mm,Y:±5mm,θ:±2.8° • **Machine Dimension:** 992 x 1305 x 1430 mm • **Printing Speed:** 1 - 100 mm/s • **Printing Accuracy:** ± 0.025 mm • **Printing Repeat Accuracy:** ± 0.025 mm • **Image Repeat position accuracy:** ±0.02 mm • **Cycle time:** 12-18 s/p • **Transfer direction:** L-R, R-L, L-L, R-R • **Air pressure:** 0.6 - 0.7 Mpa • **Applicable scraper length:** 200 - 450 mm • **Board margin gap:** 5 mm • **Transfer speed:** 0 - 400 mm/s • **Printing stroke:** 420 mm • **Operating system:** Linux	1
D.	**Solder Reflow Oven** • **Product name:** Solder Reflow Oven • **Heating Zones:** Upper 3 / down 3 • **Conveyor speed:** 15 - 60 cm/min (6 - 23 inch/min) • **Transmission:** Track • **Standard Max Height:** Upper: 26 cm / Down: 10 cm • **Heat-up time:** Approx. 15 min • **Operation direction:** left to right • Max Rated Power**:** 2000W • **Temperature:** Room temperature ~ 300°C • **Temperature control accuracy:** ±0.5°C • **PCB temperature distribution deviation:** ± 1°C • **Soldering width:** 260 mm (10 inch) • **Length process chamber:** 680 mm (26.8 inch)	1

	● **Heating type:** Nichrome wire and aluminum alloy heating	
E.	**Offline AOI Machine** ● Application: After stencil printing, pre/post reflow oven, pre/post wave soldering, FPC etc. ● Program Mode: Manual programming, auto programming, CAD data importing ● Inspection Items: *Stencil printing: Solder unavailability, insufficient or excessive solder, solder misalignment, bridging, stain, scratch etc. *Component defect: missing or excessive component, misalignment, uneven, edging, opposite mounting, wrong or bad component etc. *DIP: Missing parts, damage parts, offset, skew, inversion, etc *Soldering defect: excessive or missing solder, empty soldering, bridging, solder ball, IC NG ,copper stain etc. ● Calculation Method :Machine learning, colour calculation, colour extraction, gray scale operation, image contrast, OCV/OCR etc. ● Inspection Mode: PCB fully covered, with array and bad marking function ● SPC Statistics Function: Fully record the test data and make analysis, with high flexibility to check production and quality status ● Minimum Component: 01005 chip, 0.3 pitch IC ● Camera Lens Resolution: 5 million pix full color high speed industrial digital camera , 20 million pix camera optional 10um/15um/18um/20um/25um, can be custom-made ● Lighting Source : Annular stereo multi-channel color light, RGB/RGBW/RGBR/RWBR optional ● CPU: Intel E3 or same level ● RAM: 16GB ● HDD: 1TB , (SSD optional) ● OS: Win 7.1, 64bit ● Monitor: 22‘, 16:10 ● Moving and Inspection: Manual taking board in and out, Y servo motor driving PCB, X servo motor driving ● Mechanical System; Mode: camera ● PCB Dimension: 20*20mm(Min) ~ 450*350mm(Max), can be customized ● PCB Thickness: 0.3 ~ 5.0mm ● PCB Weight: Max: 3KG ● PCB Edge: 3mm, can be custom-made base on need ● PCB Bending: <5mm or 3% of PCB Diagonal length ● PCB Component Height: Top: 35mm, Bottom: 75mm Adjustable, can be custom-made base on need ● XY Driving System: AC servo motor, precise ball screw ● XY Moving Speed :Max: 830mm/s ● XY Positioning Accuracy: <8um	1

	• Machine Dimension: L1200 * W900 * H1500 mm • Power: AC220V, 50/60Hz, 1.2KW • PCB Height from Ground: 820±20mm • Safety Standard :CE safety standard • Environment Temperature and Humidity: 10 ~ 35 C, 35 ~ 80% RH (non condensing) • Configuration: Maintenance station, offline programming system, SPC servo, bar code	
F	**SMT Conveyor** Parameter • Power supply: Single Phase 220V 50/60HZ 100W • Conveyor Length: 150 cm • Conveying Belt: ESD belt • Conveying speed: 0.5 to 400mm/min Specification • Packing Size : 1600*260*730mm • PCB available width (mm) : 30-300 • PCB available length (mm): 50-670 • G.W. (kg): 65	1
G.	**PCB Loader Machine** Specification • PCB size(L*W): 50*50mm-350*250mm • Dimension(L*W*H): 1370*770*1250mm • Magazinesize(L*W*H): 355*320*563mm • Magazine change over time: Approx. 25 seconds • Power source & consumption: 100-230VAC (customized), 1ph, max 300VA • Air pressure & consumption: 4-6bar, max 10L/min • Transport height(mm): 900±30 (or customized) • Transport direction: L→R or R→L • PCB thickness(mm): Min 0.4mm • Magazine number: Transport up: 1pcs, Transport down: 2pcs (or customized) • Step pitch select: 10mm, 20mm, 30mm, 40mm • Weight(kg): 145kg	1
H.		1

	PCB Unloader Machine ● PCB size: (L*W): 50*50-350*250mm ● Dimension:(L*W*H): 1730*770*1250mm ● Magazine size(L*W*H) : 355*320*563mm ● Magazine change over time: Approx.25 seconds ● Power source & consumption: 100-230VAC (customized), 1ph, max 300VA ● Air pressure & consumption: 4-6bar, max 10L/min. ● Transport height(mm): 900±20 (or customized) ● Transport direction: L→R or R→L ● PCB thickness(mm): min 0.4mm ● Magazine number: Transport up: 1pcs, Transport down: 1pcs (or customized) ● Step pitch select: 1-4 (10mm step pitches) ● Weight(kg): 185kg	
I.	Ultrasound **PCB Cleaning Machine with standard accessories**	1
J.	**Automatic BGA Rework Station**	1
K.	**PCB Magazine Racks-** PCB Slot 50 or More	1
L.	**PTH Machine** ● Machine should have enough tanks for pre-galvanic treatment and plating purpose. ● Suitable number of tanks should be available for pre-galvanic treatment. (Approx. Tank Capacity 10 Lits) ● 1 galvanic plating tanks should be available for Cu plating. (Approx. Tank Capacity 30-35 Lits) ● Tanks should be made of non-corrosive material such as PVC . ● All the tanks should have proper lids. ● Plating tank should have mechanism for air injection to generate bubbles. ● All the above-mentioned tanks should have board movement system with adjustable speed. ● The tanks should have timer with audio time out and digital display. ● Rectifier for galvanic plating should have a minimum of 20 A current capacity with adjustable current and voltage. ● All the necessary accessories like anodes, anode holders, PCB holder (and the chemicals should be provided. The chemistry required for the complete PTH operation should be available in India as per requirements. Machine dimensions ● Should support board size of 210 x 300 mm	1

3. TENDER PUBLICATION AND BID SCHEDULE

- Publication: The NIT and complete bidding document is available on the official website _____/State Govt. e-procurement portal _____/ portal_____. The bidding document can be downloaded free of cost from the link provided in the said URLs.
- Submission Period and Corrigenda: The bids completed in every aspect should be submitted in the mode prescribed in Section 6.0 of this document within **21 days** from the date of publication of the notice.

4. ELIGIBILITY AND QUALIFICATION REQUIREMENTS

- The bidder shall be a legally registered entity, such as a company, LLP, partnership firm, proprietorship or other legally recognised business entity, and shall submit valid registration / constitution documents.
- The bidder shall hold a valid GSTIN. Any claim of exemption from GST registration shall be supported by the relevant statutory provision and documentary evidence and shall be subject to verification and acceptance by SOA-CII.
- The bidder shall have successfully supplied and/or installed similar item during the last three financial years. Documentary evidence such as purchase orders and completion / installation / performance certificates shall be submitted. Any higher experience threshold, if required, must be specifically justified and approved before publication.
- The bidder shall demonstrate its capability to deliver, install, test, commission and provide after-sales support for the offered equipment within the specified timeline.
- For equipment not manufactured by the bidder, the bidder shall submit valid OEM authorisation / dealership / distributorship documentation and OEM warranty support, as applicable.
- The bidder shall not be under a current order of debarment / suspension by the procuring entity or any competent government authority, to the extent applicable under the tender conditions and law.

5. TWO-BID SYSTEM AND CONTENTS OF BIDS

Bids shall be submitted simultaneously in two separate sealed envelopes, one containing the Technical Bid and the other containing the Financial Bid. The Technical Bid shall contain all technical details and relevant commercial terms and conditions and other details as specified in section 5.1, but shall not disclose the bidder's quoted prices. The Financial Bid shall contain the prices for the items offered and other details as specified in section 5.2.

5.1 Technical Bid – documents to be submitted

- Covering letter signed by the authorised signatory.
- Entity registration / constitution documents and PAN.
- GST registration certificate / applicable exemption declaration and supporting evidence.
- Company profile and details of manufacturing / supply / installation capability.
- Similar work orders and completion / performance certificates.
- OEM authorisation / dealership certificate, wherever applicable.
- Duly completed technical compliance statement against each specification in Annexure A, with documentary brochures / datasheets.

- Delivery, installation, testing, commissioning and training plan.
- Warranty and service-support commitment, including response time and service location.
- Acceptance of tender terms and conditions, or a separately identified list of deviations, if deviations are permitted by the tender. Unstated deviations shall not be presumed accepted.
- A Declaration in the applicable non-judicial stamp paper duly notarized relating to Code of Integrity, conflict of interest and debarment / suspension

5.2 Financial Bid – documents to be submitted

- Duly completed and signed item-wise price schedule in Annexure B.
- Basic price, applicable GST, freight / insurance, packing, forwarding, installation, commissioning, training and all other charges shown separately.
- Total quoted price, both in figures and words.
- Separately quoted AMC / CMC charges for the post-warranty period, as requested in the price schedule.

6. MODE AND PROCEDURE FOR SUBMISSION OF BIDS

- Bidders shall submit their bids under a two-bid system in separate sealed envelopes. The first envelope shall be marked "TECHNICAL BID – [Tender Reference No. and Equipment Name]". The second envelope shall be marked "FINANCIAL BID – [Tender Reference No. and Equipment Name]".
- Both sealed envelopes shall be placed inside one sealed outer envelope clearly marked "BID FOR SUPPLY, INSTALLATION, TESTING AND COMMISSIONING OF _____ (equipment name)", together with the Tender Reference Number, bidder's name and address.
- The sealed outer envelope shall be submitted by Registered Post / Speed Post / authorised courier or delivered by hand to the address below, so as to reach on or before the stipulated deadline. The bidder shall be responsible for ensuring timely delivery. Dispatch by post or courier shall not be treated as receipt.
- Address for submission: The Director, SOA-CII (SOA Centre for Innovation & Incubation), ITER Campus-1, 1st Floor, Sports Complex, Khandagiri/Jagamara, Bhubaneswar – 751030.
- Bids received after the prescribed date and time shall not be considered. No bid submitted by email shall be accepted under this physical-submission procedure.

7. OPENING OF BIDS AND ATTENDANCE OF BIDDERS

- Technical Bids shall be opened at the date, time and place to be notified separately by SOA-CII to the bidders. The opening shall be conducted by the duly constituted Tender Opening Committee / authorised officials, who shall record the names of bidders, receipt details and other particulars required for the opening proceedings.
- The Financial Bid envelopes shall remain sealed and in secure custody until the technical evaluation is completed and the list of technically qualified bidders is approved by the competent authority.
- Only the Financial Bids of technically qualified bidders shall be opened for further evaluation.
- The bidders or their authorized representatives may present physically during opening of Technical and Financial Bids. However, their absence shall not prevent the committee from proceeding.

8. EVALUATION OF BIDS

8.1 Preliminary scrutiny

The committee shall examine whether bids have been received within the deadline, are properly sealed and signed, contain the required documents and are substantially responsive to the tender conditions. Clarifications may be sought only in accordance with applicable procurement rules and without permitting a bidder to alter its price or modify its bid.

8.2 Technical evaluation

Technical evaluation shall be carried out against the requirements disclosed in the tender, including:

- Compliance with each mandatory technical specification and required accessories.
- Eligibility, experience and technical capability of the bidder.
- OEM authorisation and product authenticity, where applicable.
- Delivery, installation, commissioning and training capability.
- Warranty, service support and response commitments.
- Completeness of the technical submission and acceptance of material tender conditions.

The committee shall prepare a reasoned technical evaluation statement identifying each bidder as technically qualified or not qualified, with reasons for any rejection / disqualification. Any demonstration or clarification shall be conducted consistently and recorded.

8.3 Financial evaluation

- Financial Bids of only technically qualified bidders shall be opened.
- Financial evaluation shall be based on the combined evaluated price of the complete requirement or the selected group of items proposed for award. AMC / CMC charges shall be quoted separately and excluded from L1 evaluation unless specified otherwise in the Schedule of Requirements.
- The L1 bidder shall be determined for the complete requirement or selected group of items, as applicable, based on the lowest evaluated responsive price. The selected group shall be awarded to a single bidder and shall not be split among multiple vendors.

9. PERFORMANCE SECURITY

- The successful bidder shall furnish Performance Security equivalent to 3% of the value of the contract awarded, within 10 days of issue of the Letter of Award / Purchase Order.
- Performance Security may be furnished in any of the following forms: Insurance Surety Bond, account-payee Demand Draft, Fixed Deposit Receipt, Bank Guarantee / e-Bank Guarantee from a scheduled commercial bank, or online payment in an acceptable form.
- Eligible Micro and Small Enterprises (MSEs) and start-ups shall be allowed concessional Performance Security at 25% of the amount prescribed for normal bidders, subject to submission and verification of valid supporting documents.
- Performance Security shall remain valid for 60 days beyond completion of all contractual obligations of the supplier, including warranty obligations. The bidder shall extend the validity where the contractual completion or warranty period is extended.

- Performance Security shall be released after completion of all contractual obligations and expiry of the required validity period, subject to certification by SOA-CII that there are no outstanding claims or recoveries. No interest shall be payable.

10. PAYMENT TERMS

- 80% of the contract price shall be released after delivery of the equipment at the designated site, verification of quantities and submission of a valid invoice, subject to the contract terms.
- The balance 20% shall be released after successful installation, testing, commissioning, demonstration and acceptance of the equipment by SOA-CII.
- All payments shall be subject to applicable statutory deductions, submission of required documents and certification by the authorised officer / committee.

11. DELIVERY, INSTALLATION, COMMISSIONING AND TRAINING

The equipment shall be delivered, installed, tested and commissioned within 45 days from the date of issue of Purchase Order, unless a different period is specified in the Schedule of Requirements. The vendor shall provide onsite training to designated users covering operation, routine maintenance and troubleshooting. Any delay or request for extension shall be notified in writing with reasons and shall be subject to approval by the competent authority.

12. WARRANTY AND AFTER-SALES SUPPORT

- The supplied equipment shall carry a minimum one-year comprehensive onsite warranty commencing from the date of successful installation, commissioning and acceptance. Where the OEM provides a longer warranty, the bidder shall pass on the full OEM warranty to SOA-CII.
- Warranty shall cover parts (excluding normal consumables), labour, repair / replacement of defective components and service support at no additional cost, except for exclusions expressly identified in the tender and accepted by SOA-CII.
- Consumables and normal wear-and-tear items may be excluded from warranty; however, premature failure attributable to manufacturing defect or improper installation shall be covered.
- The bidder shall state its service response time, escalation contact and service arrangements in the Technical Bid. For this tender, the maximum response time shall not exceed 72 hours from receipt of a complaint, unless a stricter requirement is stated in the Schedule of Requirements.

13. AMC / CMC

Bidders shall quote AMC / CMC charges separately for each of the three to five years following expiry of the warranty period, as requested in the Financial Bid schedule. The scope, exclusions, visit frequency, uptime commitment, spare-parts coverage and escalation arrangements shall be clearly stated. AMC / CMC shall be optional unless expressly included in the Schedule of Requirements and contract award.

14. INSPECTION, TESTING AND ACCEPTANCE

- The equipment shall be inspected and accepted only after verification of supplied items and accessories against the contract, successful installation and commissioning, demonstration of specified performance and verification against the technical specifications.
- SOA-CII may conduct inspection at the supplier's premises or at site, where stated in the tender or considered necessary under the contract.

- Any defect, shortfall or non-conformity shall be notified to the supplier, who shall rectify or replace the affected item within the time specified by SOA-CII at no additional cost, where covered by the contract.

15. PACKING, TRANSPORTATION AND DELIVERY

The vendor shall be responsible for safe packing, forwarding, transportation, transit insurance, loading, unloading and delivery at the designated site. All such costs shall be included in the quoted price. No additional charges shall be payable unless expressly approved through a written contract amendment.

16. SINGLE-BID / SINGLE TECHNICALLY QUALIFIED BID SITUATION

The receipt of only one bid, or the situation where only one bidder remains technically qualified, shall not by itself be treated as lack of competition. Such bid may be considered only after the procuring authority records that: (a) the procurement was adequately advertised and sufficient time was given for submission; (b) the qualification criteria were not unduly restrictive; and (c) the price is reasonable in comparison with prevailing market values. Before acceptance, approval of the next higher authority shall be obtained and the prescribed certificate shall be recorded.

17. NO PARTIAL AWARD

The contract shall be awarded as a complete package to a single successful bidder. Partial award, item-wise award or lot-wise award shall not be permitted. Bidders shall quote for all items and components specified in the Schedule of Requirements. Bids offering only part of the required scope shall be treated as non-responsive and may be rejected.

18. RISK, DEFAULT AND CONTRACT PERFORMANCE

If the successful bidder fails to supply or perform the contract within the agreed period, or otherwise commits a material breach, SOA-CII may take action in accordance with the contract, including termination, recovery of losses where legally recoverable, invocation of Performance Security and procurement from an alternative source at the risk and cost of the defaulting supplier, after following the applicable contractual procedure.

19. CODE OF INTEGRITY, CONFLICT OF INTEREST AND DEBARMENT

Bidders shall comply with the Code of Integrity and shall disclose any actual or potential conflict of interest. Bidders shall submit the declarations prescribed in Annexure D. Any action relating to corrupt, fraudulent, collusive, coercive or obstructive practices, conflict of interest, or debarment / suspension shall be dealt with under the applicable procurement requirements and law, after following the required procedure.

20. RIGHT TO ACCEPT OR REJECT BIDS

SOA-CII reserves the right to accept or reject any bid, reject all bids, or cancel the tender process, where permitted by applicable procurement requirements and for reasons recorded in writing. Any such decision shall be taken by the competent authority in accordance with the applicable requirements and the conditions of this tender. The procuring entity shall not make arbitrary or discriminatory decisions.

21. AWARD OF CONTRACT

Subject to completion of evaluation, verification, availability of funds and approval of the competent authority, the contract shall be recommended for award to the L1 bidder for the complete requirement or selected group of items, as applicable, in accordance with Clause 8.3.The successful bidder shall be issued a Letter of Award / Purchase Order specifying the accepted scope, price, delivery schedule, warranty, Performance Security and other contractual conditions. The bidder shall acknowledge and accept the award within the period stated in the Letter of Award.

22. GENERAL CONDITIONS

- The bidder shall carefully examine the tender document and seek clarification in writing before the clarification deadline stated in the NIT.
- Any deviation, assumption or condition introduced by the bidder shall be clearly identified in its bid. Material deviations may render the bid non-responsive.
- The bidder shall bear all costs associated with preparation and submission of its bid. SOA-CII shall not be responsible for such costs.
- The bidder shall keep its offer valid for 90 days from the last date prescribed for receipt of bids. Any extension of bid validity shall be sought and handled in accordance with the applicable procurement instructions.
- The contract shall be governed by the laws applicable in India. The place of jurisdiction shall be Bhubaneswar, Odisha, subject to applicable law and the final contract.

ANNEXURE A – TECHNICAL SPECIFICATIONS AND COMPLIANCE STATEMENT

Bidders shall reproduce / complete the compliance column against every specification. Supporting datasheets and brochures shall be attached.

Sl. No.	Required Specification / Parameter	Minimum Requirement	Offered Specification	Complied (Yes/No)	Document / Page Reference
1	[Insert]	[Insert]	[Bidder to fill]	[ ]	[ ]
2	[Insert]	[Insert]	[Bidder to fill]	[ ]	[ ]
3	[Insert]	[Insert]	[Bidder to fill]	[ ]	[ ]
4	[Insert]	[Insert]	[Bidder to fill]	[ ]	[ ]
5	[Insert]	[Insert]	[Bidder to fill]	[ ]	[ ]

Bidder's declaration: We confirm that the offered equipment complies with the requirements stated above, except for deviations specifically disclosed in the attached deviation statement.

Authorised Signatory: _____ Name: _____ Date: _____

Siksha 'O' Anusandhan
(Deemed to be University)

CII
Center for Inovation and Incubation

ANNEXURE B – FINANCIAL BID / PRICE SCHEDULE

This Annexure shall be placed only in the sealed Financial Bid envelope. Do not include prices in the Technical Bid.

Sl. No.	Item / Equipment Description	Qty.	Basic Unit Price (₹)	Basic Total (₹)	GST (₹)	Other Charges (₹)	Total Evaluated Price (₹)
1	[Insert item]	[ ]	[ ]	[ ]	[ ]	[ ]	[ ]
2	[Insert item]	[ ]	[ ]	[ ]	[ ]	[ ]	[ ]
3	[Insert item]	[ ]	[ ]	[ ]	[ ]	[ ]	[ ]
	Grand Total						[ ]

Other charges shall include packing, forwarding, freight, transit insurance, delivery, installation, commissioning, training and any other mandatory charges. The bidder shall itemise each component.

AMC / CMC Period	Annual Charge (₹)	GST (₹)	Total Annual Charge (₹)	Scope / Coverage
Year 1	[ ]	[ ]	[ ]	[ ]
Year 2	[ ]	[ ]	[ ]	[ ]
Year 3	[ ]	[ ]	[ ]	[ ]
Year 4 (if quoted)	[ ]	[ ]	[ ]	[ ]
Year 5 (if quoted)	[ ]	[ ]	[ ]	[ ]

Total quoted amount in figures: ₹ _____

Total quoted amount in words:

_____

Bid validity: 90 days from the last date prescribed for receipt of bids Delivery period: _____ days

Authorised Signatory: _____ Name / Designation: _____ Seal: _____

Siksha 'O' Anusandhan
(Deemed to be University)

CII
Center for Inovation and Incubation

ANNEXURE D – BIDDER DECLARATIONS

(To be submitted on the bidder's letterhead, duly signed and stamped)

Tender Reference No.: _____

Date: _____

We, the undersigned, being duly authorised to represent the bidder, hereby declare that:

1. The information and documents submitted with this bid are true, complete and correct to the best of our knowledge. No material information has been knowingly concealed.

2. We shall comply with the applicable Code of Integrity and shall not engage in bribery, corruption, fraud, collusion, coercion, obstruction or any other prohibited practice in connection with this procurement.

3. We have disclosed below any actual or potential conflict of interest that may affect our participation in this tender. If no such conflict exists, we have stated "Nil".

4. We are not currently debarred or suspended by SOA-CII or any competent Government authority from participating in procurement, to the extent applicable. Details of any relevant past or current debarment / suspension are disclosed below.

5. We have not offered, promised or given any undue gratification or benefit to any person connected with this procurement, and we shall promptly disclose any attempt to influence the procurement process.

6. We understand that any false declaration, material misrepresentation or breach of these commitments may result in rejection of our bid or other action in accordance with the tender conditions and applicable law.

Details of conflict of interest / debarment / suspension, if any (otherwise write "Nil"):

_____

_____

Authorised Signatory: _____

Name: _____ Designation: _____

Company Name: _____

Signature & Seal: _____ Date: _____